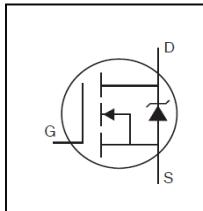


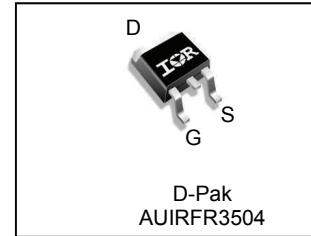
Features

- Advanced Planar Technology
- Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified *



HEXFET® Power MOSFET

V_{DSS}	40V
R_{DS(on)}	typ. 7.8mΩ
	max. 9.2mΩ
I_D (Silicon Limited)	87A®
I_D (Package Limited)	56A



G	D	S
Gate	Drain	Source

Description

Specifically designed for Automotive applications, this Stripe Planar design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRFR3504	D-Pak	Tube	75	AUIRFR3504
		Tape and Reel Left	3000	AUIRFR3504TRL

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

Symbol	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)	87⑧	A
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)	61⑧	
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V (Package Limited)	56	
I _{DM}	Pulsed Drain Current ①	350	
P _D @ T _C = 25°C	Maximum Power Dissipation	140	W
	Linear Derating Factor	0.92	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy (Thermally Limited) ②	240	mJ
E _{AS} (Tested)	Single Pulse Avalanche Energy Tested Value ⑥⑦	480	
I _{AR}	Avalanche Current ①	See Fig.15,16, 12a, 12b	
E _{AR}	Repetitive Avalanche Energy ⑤	mJ	
T _J	Operating Junction and	-55 to + 175	°C
T _{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds (1.6mm from case)		

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
R _{θJC}	Junction-to-Case ⑩	—	1.09	°C/W
R _{θJA}	Junction-to-Ambient (PCB Mount) ⑨	—	50	
R _{θJA}	Junction-to-Ambient	—	110	

HEXFET® is a registered trademark of Infineon.

*Qualification standards can be found at www.infineon.com

Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	40	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.041	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance	—	7.8	9.2	$\text{m}\Omega$	$V_{GS} = 10\text{V}, I_D = 30\text{A}$ ④**
$V_{GS(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
g_{fs}	Forward Trans conductance	40	—	—	S	$V_{DS} = 10\text{V}, I_D = 30\text{A}$ ④**
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}$
		—	—	250		$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	200	nA	$V_{GS} = 20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-200		$V_{GS} = -20\text{V}$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

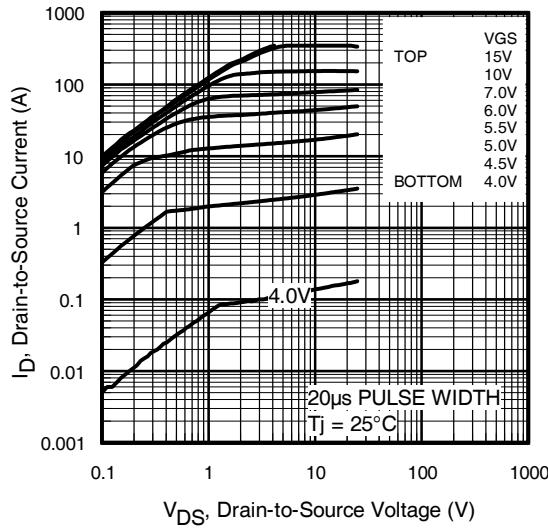
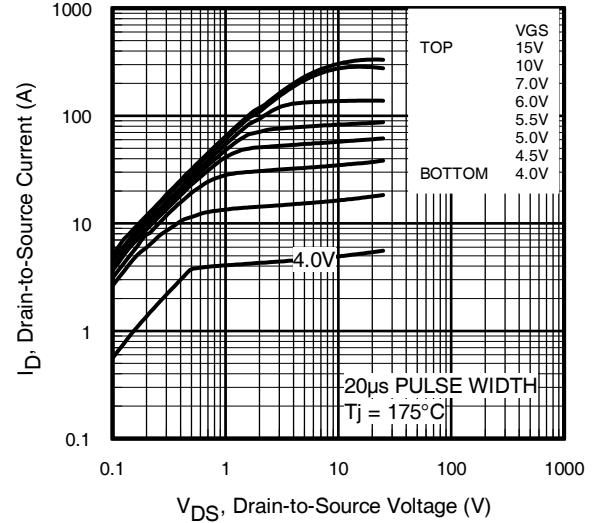
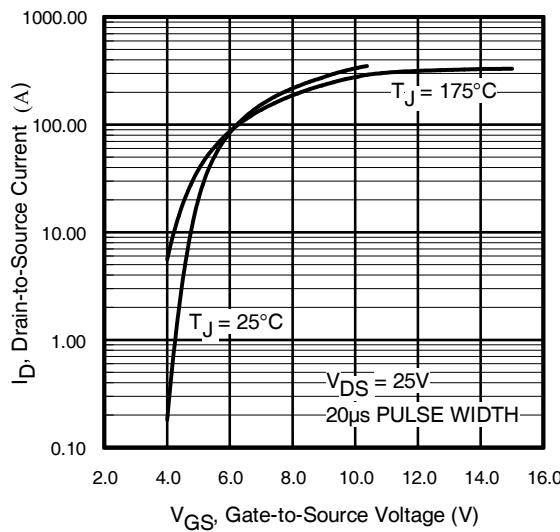
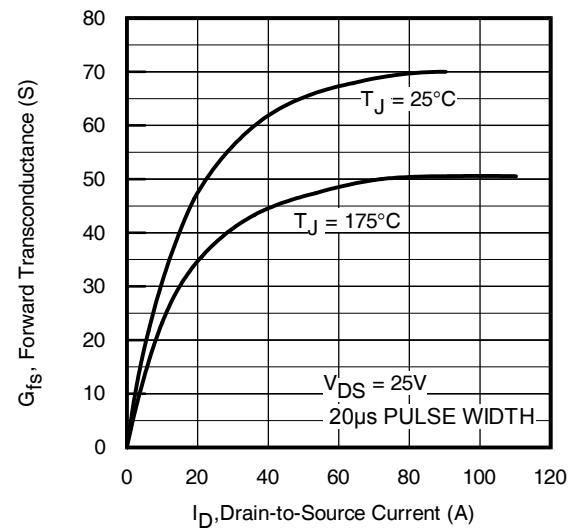
Q_g	Total Gate Charge	—	48	71	nC	$I_D = 30\text{A}^{**}$
Q_{gs}	Gate-to-Source Charge	—	12	18		$V_{DS} = 32\text{V}$
Q_{gd}	Gate-to-Drain Charge	—	13	20		$V_{GS} = 10\text{V}^④$
$t_{d(on)}$	Turn-On Delay Time	—	11	—		$V_{DD} = 20\text{V}$
t_r	Rise Time	—	53	—		$I_D = 30\text{A}^{**}$
$t_{d(off)}$	Turn-Off Delay Time	—	36	—	ns	$R_G = 6.8\Omega$
t_f	Fall Time	—	22	—		$V_{GS} = 10\text{V}^④$
L_D	Internal Drain Inductance	—	4.5	—		Between lead, 6mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	7.5	—	nH	
C_{iss}	Input Capacitance	—	2150	—	pF	$V_{GS} = 0\text{V}$
C_{oss}	Output Capacitance	—	580	—		$V_{DS} = 25\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	46	—		$f = 1.0\text{MHz}$, See Fig.5
C_{oss}	Output Capacitance	—	2830	—		$V_{GS} = 0\text{V}, V_{DS} = 1.0\text{V}$ $f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	—	510	—		$V_{GS} = 0\text{V}, V_{DS} = 32\text{V}$ $f = 1.0\text{MHz}$
$C_{oss\ eff.}$	Effective Output Capacitance	—	870	—		$V_{GS} = 0\text{V}, V_{DS} = 0\text{V to } 32\text{V}$

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_s	Continuous Source Current (Body Diode)	—	—	87⑧	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	350		
V_{SD}	Diode Forward Voltage	—	—	1.3		$T_J = 25^\circ\text{C}, I_S = 30\text{A}^{**}, V_{GS} = 0\text{V}^④$
t_{rr}	Reverse Recovery Time	—	53	80		$T_J = 25^\circ\text{C}, I_F = 30\text{A}^{**}, V_{DD} = 20\text{V}$
Q_{rr}	Reverse Recovery Charge	—	86	130		$dI/dt = 100\text{A}/\mu\text{s}^④$
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Limited by $T_{J\max}$, starting $T_J = 25^\circ\text{C}$, $L = 0.52\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 30\text{A}$, $V_{GS} = 10\text{V}$. Part not recommended for use above this value.
- ③ $I_{SD} \leq 30\text{A}$, $dI/dt \leq 170\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$.
- ④ Pulse width $\leq 1.0\text{ms}$; duty cycle $\leq 2\%$.
- ⑤ $C_{oss\ eff.}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}
- ⑥ Limited by $T_{J\max}$, see Fig.12a, 12b, 15, 16 for typical repetitive avalanche performance.
- ⑦ This value determined from sample failure population. 100% tested to this value in production.
- ⑧ Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 56A.
- ⑨ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994
- ⑩ R_θ is measured at T_J approximately 90°C .
- ** All AC and DC test conditions based on former package limited current of 30A.

**Fig. 1** Typical Output Characteristics**Fig. 2** Typical Output Characteristics**Fig. 3** Typical Transfer Characteristics**Fig. 4** Typical Forward Trans conductance Vs. Drain Current

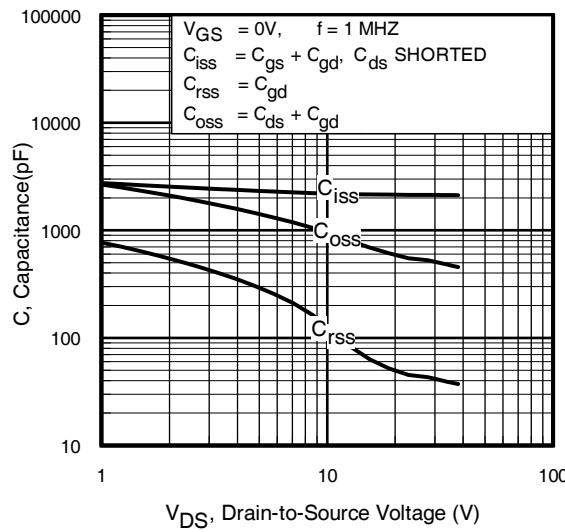


Fig 5. Typical Capacitance vs.
Drain-to-Source Voltage

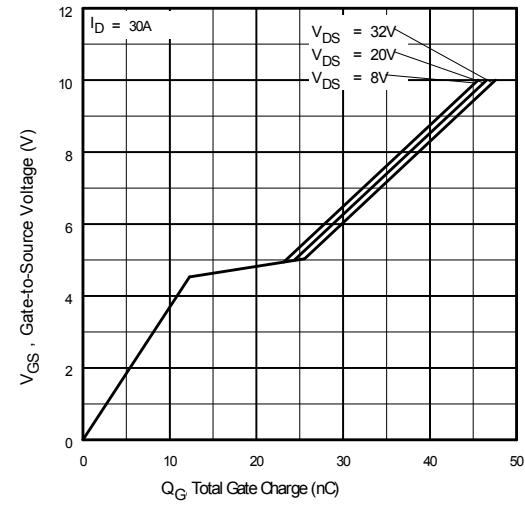


Fig 6. Typical Gate Charge vs.
Gate-to-Source Voltage

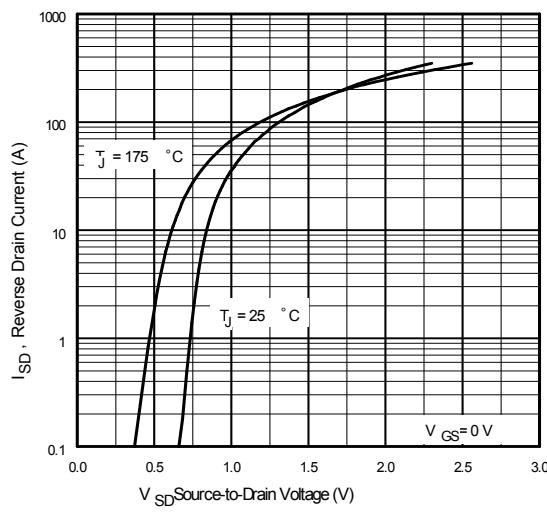


Fig. 7 Typical Source-to-Drain Diode
Forward Voltage

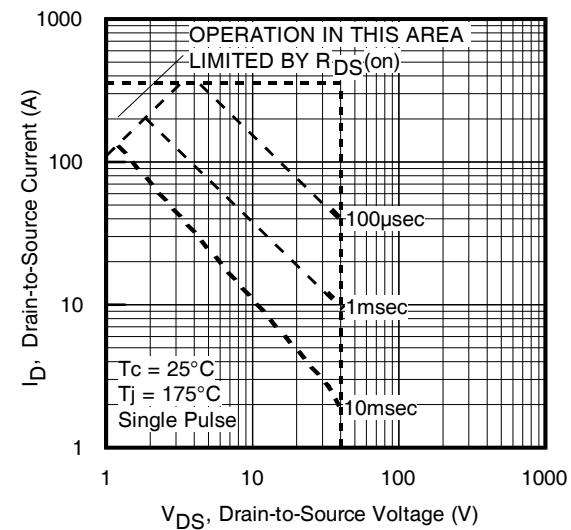


Fig 8. Maximum Safe Operating Area

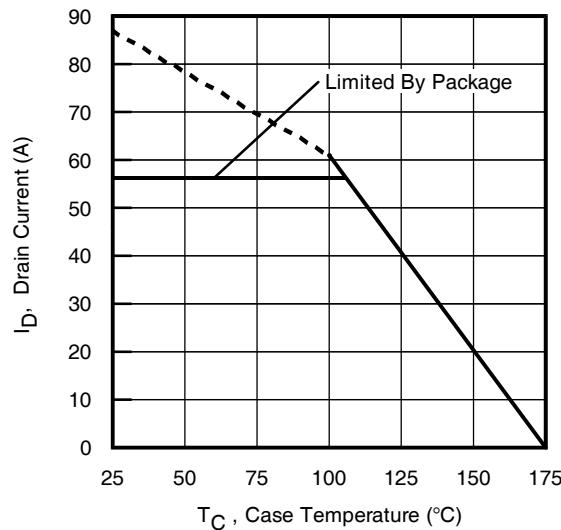


Fig 9. Maximum Drain Current Vs. Case Temperature

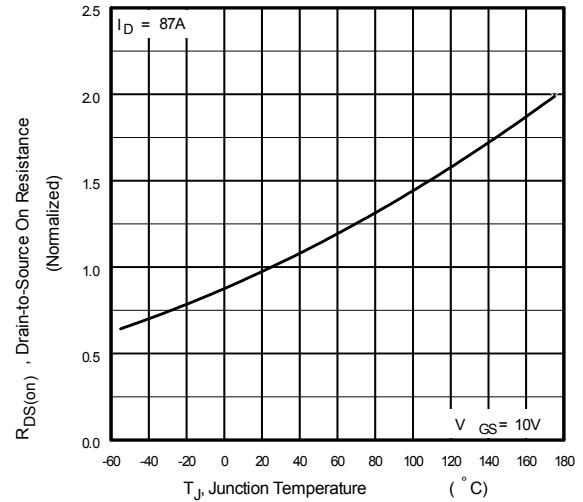


Fig 10. Normalized On-Resistance Vs. Temperature

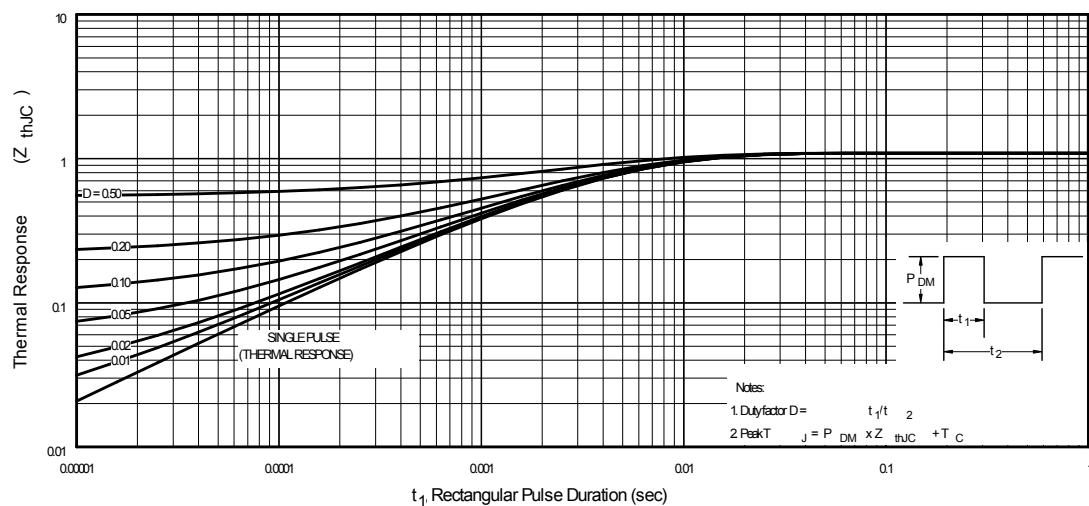


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

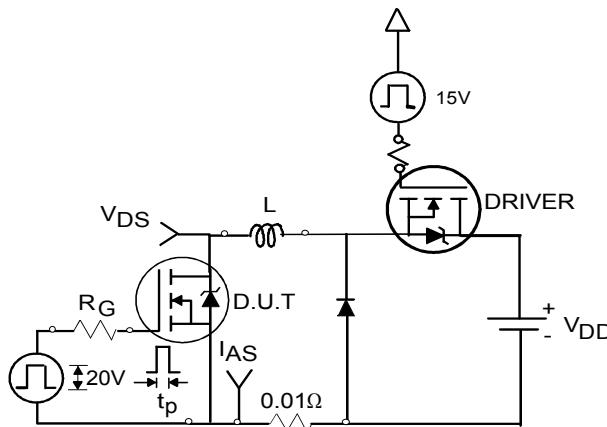


Fig 12a. Unclamped Inductive Test Circuit

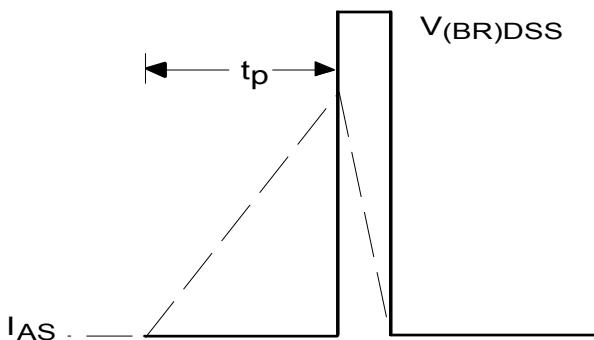


Fig 12b. Unclamped Inductive Waveforms

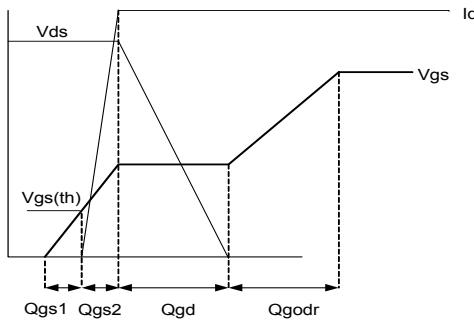


Fig 13a. Gate Charge Waveform

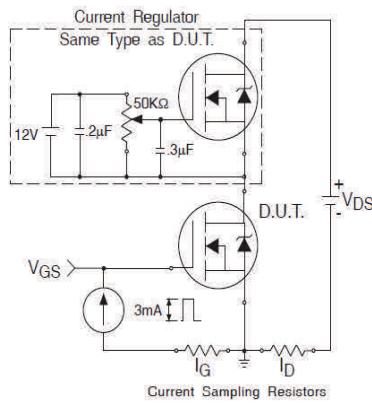


Fig 13b. Gate Charge Test Circuit

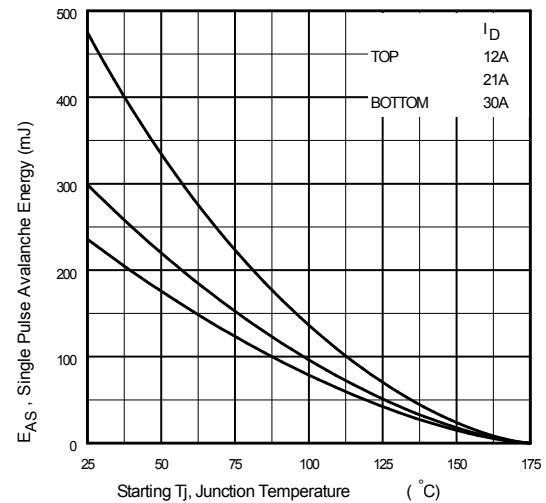


Fig 12c. Maximum Avalanche Energy vs. Drain Current

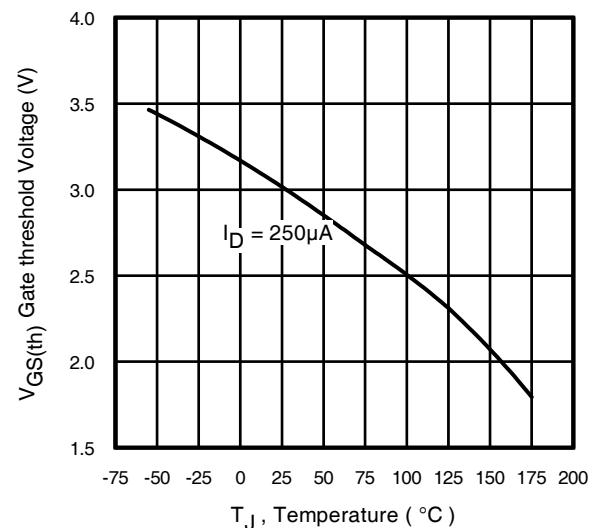


Fig 14. Threshold Voltage Vs. Temperature

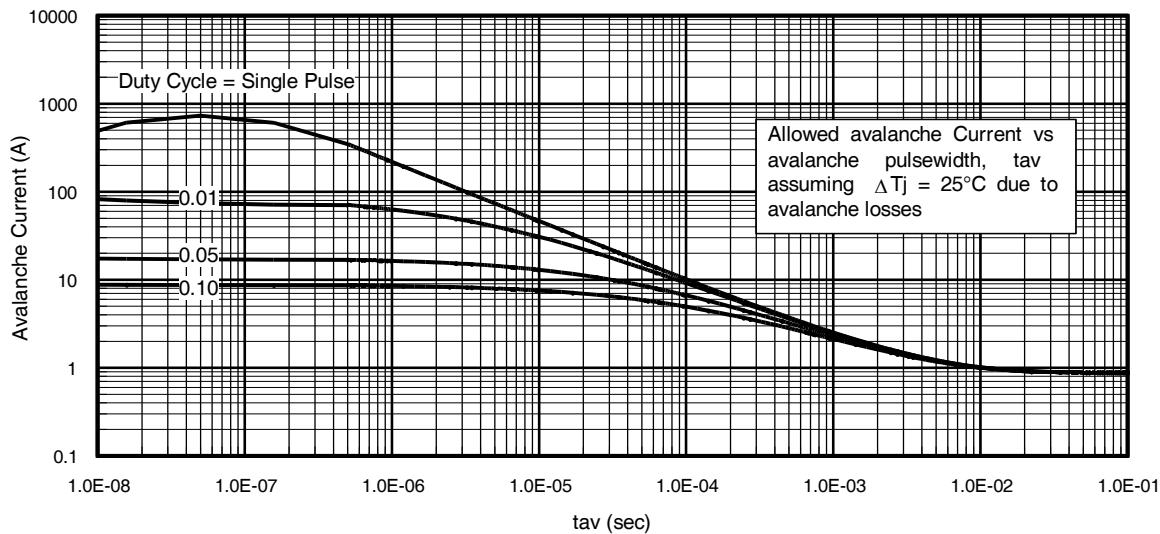


Fig 15. Typical Avalanche Current Vs. Pulse width

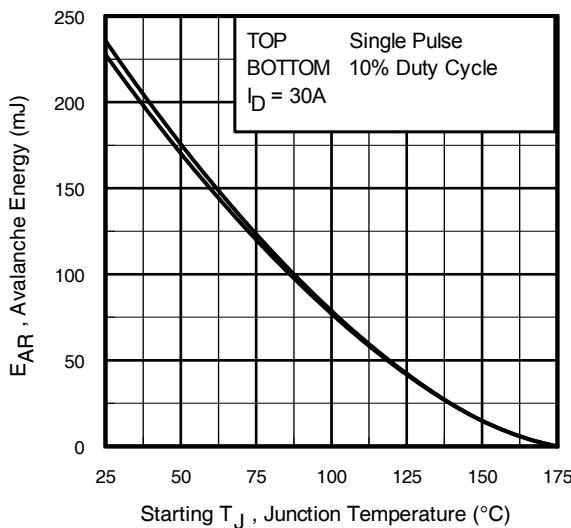


Fig 16. Maximum Avalanche Energy Vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 15, 16:

(For further info, see AN-1005 at www.infineon.com)

1. Avalanche failures assumption:
Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax} . This is validated for every part type.
 2. Safe operation in Avalanche is allowed as long as T_{jmax} is not exceeded.
 3. Equation below based on circuit and waveforms shown in Figures 12a, 12b.
 4. $P_{D(ave)}$ = Average power dissipation per single avalanche pulse.
 5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
 6. I_{av} = Allowable avalanche current.
 7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 15, 16).
- t_{av} = Average time in avalanche.
 D = Duty cycle in avalanche = $t_{av} \cdot f$
 $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see Figures 13)

$$P_{D(ave)} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$

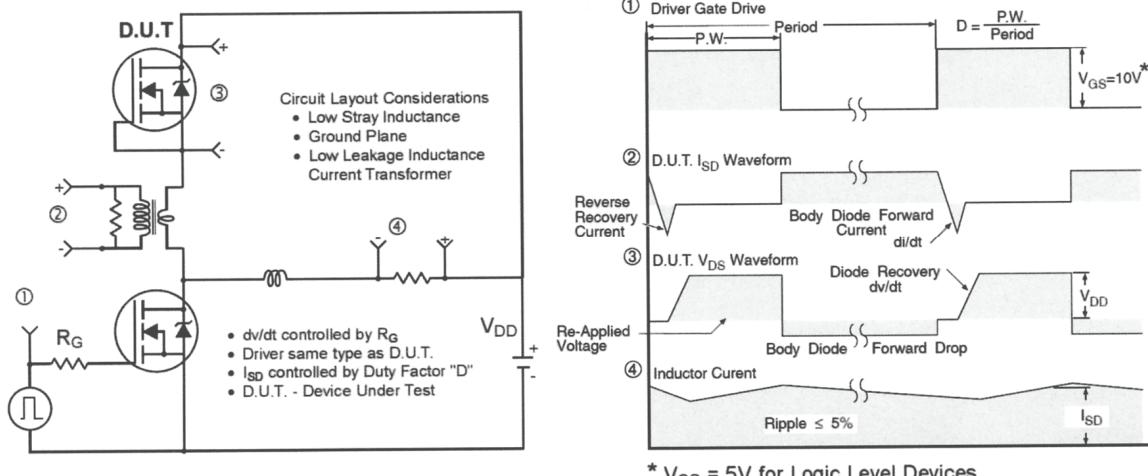


Fig 17. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

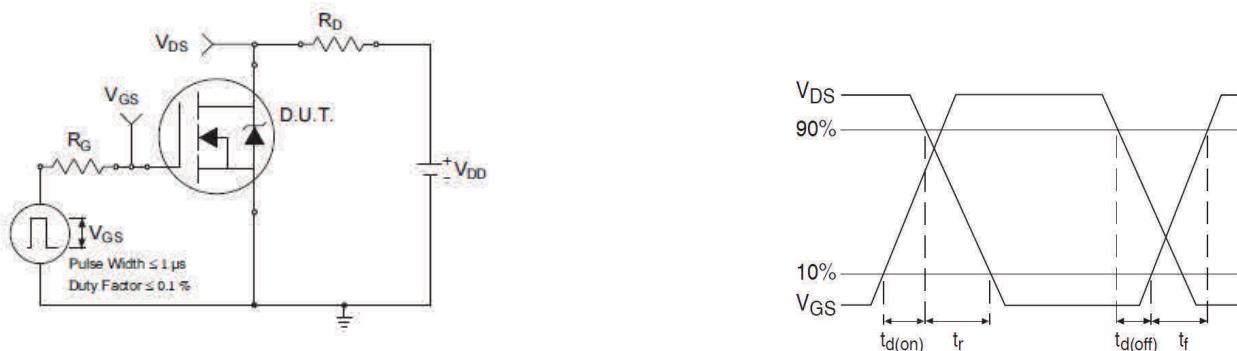
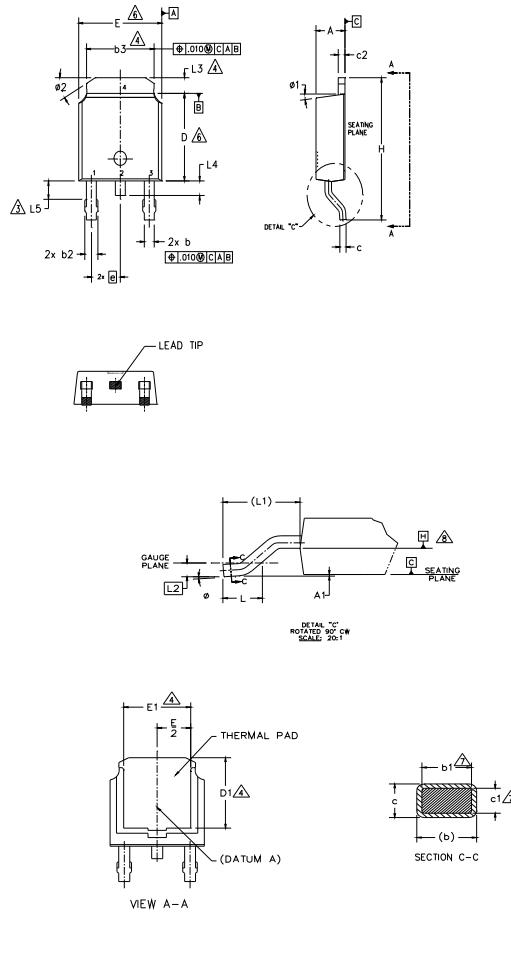


Fig 18a. Switching Time Test Circuit

Fig 18b. Switching Time Waveforms

D-Pak (TO-252AA) Package Outline (Dimensions are shown in millimeters (inches))

NOTES:

- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- 2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].
- 3.- LEAD DIMENSION UNCONTROLLED IN L5.
- 4.- DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.- SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
- 6.- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
- 7.- DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
- 8.- DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
- 9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

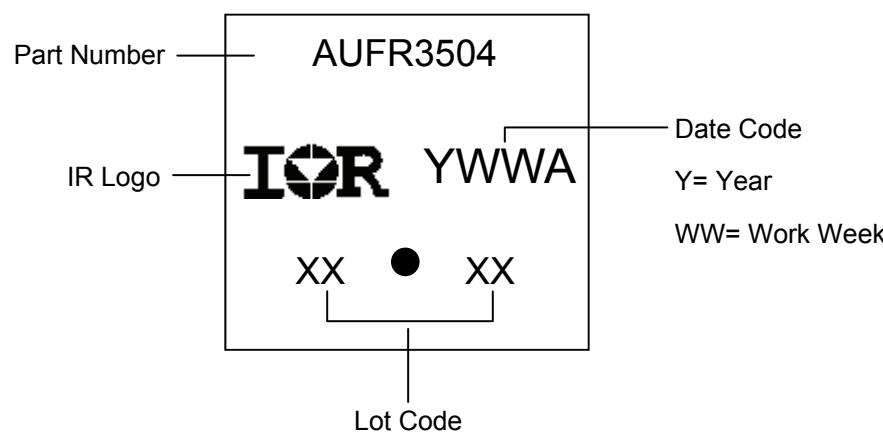
S Y M B O L	DIMENSIONS		N O T E S
	MILLIMETERS	INCHES	
	MIN.	MAX.	
A	2.18	.239	.086 .094
A1	—	0.13	— .005
b	0.64	0.89	.025 .035
b1	0.65	0.79	.025 .031
b2	0.76	1.14	.030 .045
b3	4.95	5.46	.195 .215
c	0.46	0.61	.018 .024
c1	0.41	0.56	.016 .022
c2	0.46	0.89	.018 .035
D	5.97	6.22	.235 .245
D1	5.21	—	.205 —
E	6.35	6.73	.250 .265
E1	4.32	—	.170 —
e	2.29 BSC	—	.090 BSC
H	9.40	10.41	.370 .410
L	1.40	1.78	.055 .070
L1	2.74 BSC	—	.108 REF.
L2	0.51 BSC	—	.020 BSC
L3	0.89	1.27	.035 .050
L4	—	1.02	— .040
L5	1.14	1.52	.045 .060
Ø	0°	10°	0° 10°
Ø1	0°	15°	0° 15°
Ø2	25°	35°	25° 35°

LEAD ASSIGNMENTS
HEXFET

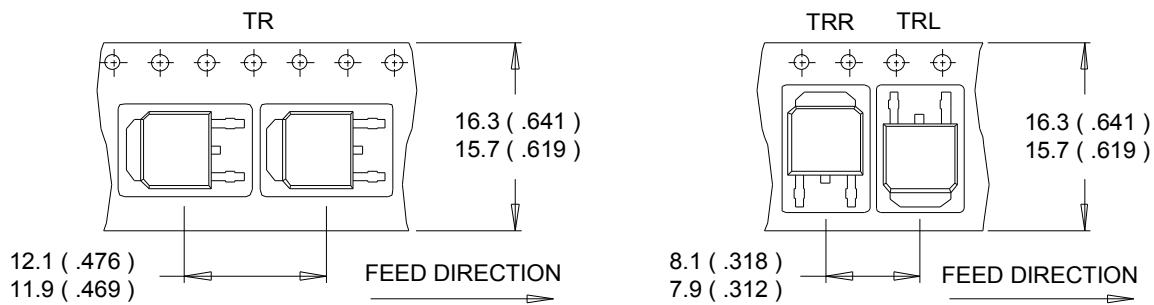
- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBT & CoPAK

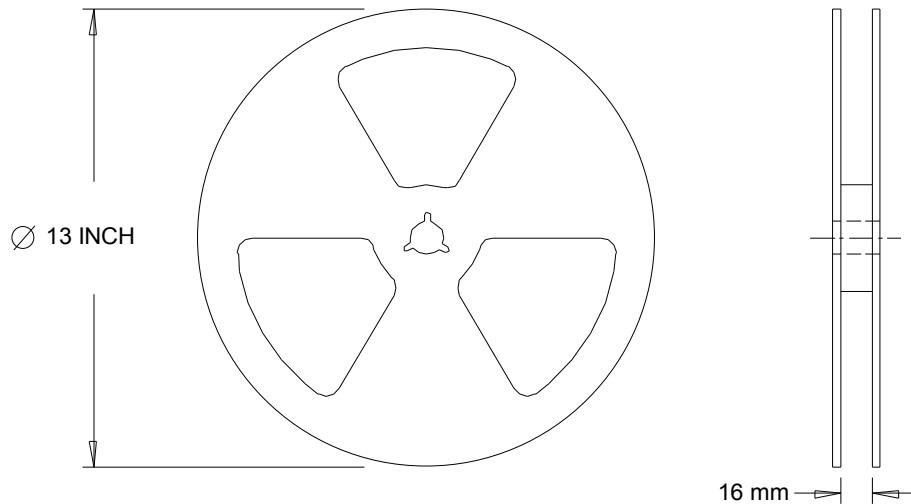
- 1.- GATE
- 2.- COLLECTOR
- 3.- Emitter
- 4.- COLLECTOR

D-Pak (TO-252AA) Part Marking Information


Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

D-Pak (TO-252AA) Tape & Reel Information (Dimensions are shown in millimeters (inches))**NOTES :**

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.

**NOTES :**

1. OUTLINE CONFORMS TO EIA-481.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Qualification Information

Qualification Level		Automotive (per AEC-Q101)	
		Comments: This part number(s) passed Automotive qualification. Infineon's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		D-Pak	MSL1
ESD	Machine Model	Class M4 (+/- 500V) [†] AEC-Q101-002	
	Human Body Model	Class H1C (+/- 1500V) [†] AEC-Q101-001	
	Charged Device Model	Class C5 (+/- 2000V) [†] AEC-Q101-005	
RoHS Compliant		Yes	

[†] Highest passing voltage.

Revision History

Date	Comments
11/23/2015	<ul style="list-style-type: none"> • Updated datasheet with corporate template • Corrected ordering table on page 1.

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- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помошь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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